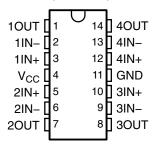
- Qualified for Automotive Applications
- ESD Protection <500 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0); 1500 V Using Charged Device Model
- ESD Human Body Model >2 kV Machine Model >200 V and Charge Device Model = 2 kV For K-Suffix Devices.
- Low Supply-Current Drain Independent of Supply Voltage . . . 0.8 mA Typ
- Low Input Bias and Offset Parameters:
 - Input Offset Voltage . . . 3 mV Typ
 - Input Offset Current . . . 2 nA Typ
 - Input Bias Current . . . 20 nA Typ

description/ordering information

This device consists of four independent high-gain frequency-compensated operational amplifiers that are designed specifically to operate from a single supply over a wide range of voltages. Operation from

- Common-Mode Input Voltage Range Includes Ground, Allowing Direct Sensing Near Ground
- Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage:
 - Non-V devices . . . 26 V
 - V-Suffix devices . . . 32 V
- Open-Loop Differential Voltage Amplification . . . 100 V/mV Typ
- Internal Frequency Compensation

D OR PW PACKAGE (TOP VIEW)



split supplies is possible when the difference between the two supplies is 3 V to 26 V (3 V to 32 V for V-suffixed devices), and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. The low supply-current drain is independent of the magnitude of the supply voltage.

Applications include transducer amplifiers, dc amplification blocks, and all the conventional operational-amplifier circuits that now can be more easily implemented in single-supply-voltage systems. For example, the LM2902 can be operated directly from the standard 5-V supply that is used in digital systems and easily provides the required interface electronics without requiring additional ± 15 -V supplies.

ORDERING INFORMATION[†]

T _A	V _{IO} max AT 25°C	MAX V _{CC}	PACK	AGE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	7\/	26 V	SOIC (D)	Reel of 2500	LM2902QDRQ1	2902Q1
	7 mV		TSSOP (PW)	Reel of 2000	LM2902QPWRQ1	2902Q1
-40°C to 125°C	7 mV	32 V	SOIC (D)	Reel of 2500	LM2902KVQDRQ1	2902KVQ
-40 C to 125 C			TSSOP (PW)	Reel of 2000	LM2902KVQPWRQ1	2902KVQ
	2 mV	32 V	SOIC (D)	Reel of 2500	LM2902KAVQDRQ1	2902KAQ
	≥ mv		TSSOP (PW)	Reel of 2000	LM2902KAVQPWRQ1	2902KAQ

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

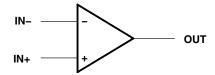


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

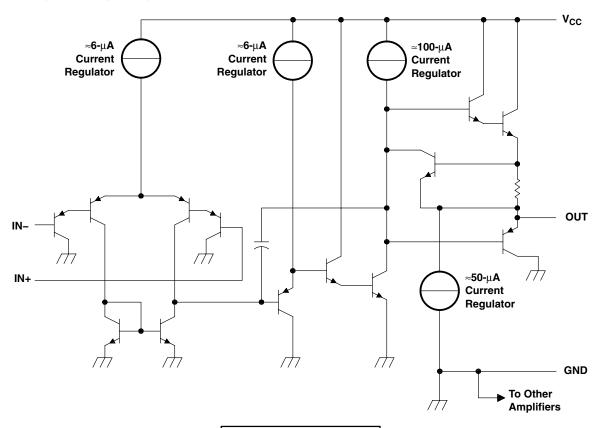


[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

symbol (each amplifier)



schematic (each amplifier)



COMPONENT COUNT (TOTAL DEVICE)								
Epi-FET	1							
Transistors	95							
Diodes	4							
Resistors	11							
Capacitors	4							



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

		LM2902-Q1	LM2902KV-Q1	UNIT
Supply voltage, V _{CC} (see Note 1)	26	32	V	
Differential input voltage, V _{ID} (see Note 2)	±26	±32	V	
Input voltage, V _I (either input)	-0.3 to 26	-0.3 to 32	٧	
Duration of output short circuit (one amplifier) to ground at (or below Note 3)	Unlimited	Unlimited		
Backers the most investment of the Material and EV	D package (0 LFPM)	101	101	0000
Package thermal impedance, θ _{JA} (see Notes 4 and 5)	PW package	113	113	°C/W
Operating virtual junction temperature, T _J	142	142	°C	
Storage temperature range, T _{stg}	-65 to 150	-65 to 150	°C	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential voltages and V_{CC} specified for the measurement of I_{OS}, are with respect to the network GND.

- 2. Differential voltages are at IN+ with respect to IN-.
- 3. Short circuits from outputs to $V_{\mbox{\footnotesize{CC}}}$ can cause excessive heating and eventual destruction.
- 4. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 142°C can affect reliability.
- 5. The package thermal impedance is calculated in accordance with JESD 51-7.



LM2902-Q1 **QUADRUPLE OPERATIONAL AMPLIFIER**

SGLS178E - AUGUST 2003 - REVISED APRIL 2008

electrical characteristics at specified free-air temperature, $V_{CC} = 5 \text{ V}$ (unless otherwise noted)

DADAMETED		TEGE COMPLETIONS	- +	LM2	2902-Q1		UNIT	
	PARAMETER	TEST CONDITIONS†	T _A ‡	MIN	TYP§	MAX	UNIT	
V	Input offeet veltere	V _{CC} = 5 V to 26 V,	25°C		3	7	mV	
V _{IO}	Input offset voltage	$V_{IC} = V_{ICR}min, V_O = 1.4 V$	Full range			10	IIIV	
	Innut offeet current	V 14V	25°C		2	50	~^	
I _{IO}	Input offset current	V _O = 1.4 V	Full range			300	nA	
	Innut high current	V 14V	25°C		-20	-250	~^	
I _{IB}	Input bias current	V _O = 1.4 V	Full range			-500	nA	
V _{ICR}	Common-mode input voltage range	V _{CC} = 5 V to 26 V	25°C	0 to V _{CC} - 1.5			٧	
VICH	Common mode input voltage failige	V _{CC} = 3 V to 20 V	Full range	0 to V _{CC} - 2			v 	
		$R_L = 10 \text{ k}\Omega$	25°C	V _{CC} – 1.5				
V_{OH}	High-level output voltage	$V_{CC} = 26 \text{ V}, \qquad R_L = 2 \text{ k}\Omega$	Full range	22			V	
		$V_{CC} = 26 \text{ V}, \qquad R_L \ge 10 \text{ k}\Omega$	Full range	23	24			
V_{OL}	Low-level output voltage	$R_L \le 10 \text{ k}\Omega$	Full range		5	20	mV	
_	Large-signal differential voltage	$V_{CC} = 15 \text{ V}, V_{O} = 1 \text{ V to } 11 \text{ V},$	25°C		100		V/mV	
A_{VD}	amplification	$R_L \ge 2 k\Omega$	Full range	15			V/IIIV	
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR}min$	25°C	50	80		dB	
k _{SVR}	Supply-voltage rejection ratio ($\Delta V_{CC}/\Delta V_{IO}$)		25°C	50	100		dB	
V_{O1}/V_{O2}	Crosstalk attenuation	f = 1 kHz to 20 kHz	25°C		120		dB	
		$V_{CC} = 15 \text{ V}, V_{ID} = 1 \text{ V},$	25°C	-20	-30	-60		
		$V_O = 0$	Full range	-10			mA	
IO	Output current	$V_{CC} = 15 \text{ V}, \qquad V_{ID} = -1 \text{ V},$	25°C	10	20		IIIA	
		V _O = 15 V	Full range	5				
		$V_{ID} = -1 \text{ V}, \qquad V_{O} = 200 \text{ mV}$	25°C		30		μΑ	
I _{OS}	Short-circuit output current	V_{CC} at 5 V, $V_{O} = 0$, GND at -5 V	25°C		±40	±60	mA	
	Cumply oursent	$V_O = 2.5 \text{ V}$, No load	Full range		0.7	1.2		
I _{CC}	Supply current (four amplifiers)	$V_{CC} = 26 \text{ V}$ $V_{O} = 0.5 \text{ V}_{CC}$, No load	Full range		1.4	3	mA	

[†] All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified. ‡ Full range is -40°C to 125°C. § All typical values are at T_A = 25°C.



electrical characteristics at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted) (continued)

2020					LM29	02KV-Q1		
	PARAMETER		DITIONS†	T _A ‡	MIN	TYP§	MAX	UNIT
		V 5.V4= 00	Non-A	25°C		3	7	
 ,,	land affect valle as	V _{CC} = 5 V to 32 V,	devices	Full range			10	\/
V_{IO}	Input offset voltage	$V_{IC} = V_{ICR}min,$ $V_{O} = 1.4 \text{ V}$	A-suffix	25°C		1	2	mV
		V _O = 1.4 V	devices	Full range			4	
$\Delta V_{IO}/\Delta T$	Temperature drift	$R_S = 0 \Omega$		Full range		7		μV/°C
I _{IO}	Input offset current	V _O = 1.4 V		25°C		2	50	nA
וי	input onset current	VO = 1.4 V		Full range			150	ПА
$\Delta I_{IO}/\Delta T$	Temperature drift			Full range		10		pA/°C
I _{IB}	Input bias current	V _O = 1.4 V		25°C		-20	-250	nA
ııB	input bias current	VO = 1.4 V		Full range			-500	ПА
V_{ICR}	Common-mode input voltage range	V _{CC} = 5 V to 32 V		25°C	0 to V _{CC} - 1.5			V
VICR	Common-mode input voltage range	ACC = 2 A 10 35 A	Full range	0 to V _{CC} - 2			V	
		$R_L = 10 \text{ k}\Omega$	25°C	V _{CC} – 1.5				
V _{OH}	High-level output voltage	$V_{CC} = 32 \text{ V}, \qquad R_L = 2 \text{ k}\Omega$		Full range	26			V
		V _{CC} = 32 V,	$I_{CC} = 32 \text{ V}, \qquad R_L \ge 10 \text{ k}\Omega \qquad \text{Full range} \qquad 27$					
V_{OL}	Low-level output voltage	$R_L \le 10 \text{ k}\Omega$		Full range		5	20	mV
۸ ـ	Large-signal differential voltage	V _{CC} = 15 V, V _O =	1 V to 11 V,	25°C	25	100		V/mV
A _{VD}	amplification	$R_L \ge 2 k\Omega$		Full range	15			V/IIIV
	Amplifier-to-amplifier coupling [¶]	f = 1 kHz to 20 kH input referred	Z,	25°C		120		dB
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR}min$		25°C	60	80		dB
k _{SVR}	Supply-voltage rejection ratio $(\Delta V_{CC}/\Delta V_{IO})$			25°C	60	100		dB
V_{O1}/V_{O2}	Crosstalk attenuation	f = 1 kHz to 20 kH	Z	25°C		120		dB
		V _{CC} = 15		25°C	-20	-30	-60	
		$V_0 = 0$	$V_{ID} = 1 V$,	Full range	-10			
lo	Output current	V _{CC} = 15		25°C	10	20		mA
		V _O = 15 V	$V_{ID} = -1 V$,	Full range	5			
		$V_{ID} = -1 V$,	V _O = 200 mV	25°C	12	40		μΑ
I _{OS}	Short-circuit output current	V _{CC} at 5 V, GND at –5 V	V _O = 0,	25°C		±40	±60	mA
		$V_0 = 2.5 V$,	No load	Full range		0.7	1.2	
I _{CC}	Supply current (four amplifiers)	$V_{CC} = 32 \text{ V}$ $V_{O} = 0.5 \text{ V}_{CC}$	No load	Full range		1.4	3	mA
L								

[†] All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified.



 $^{^{\}ddagger}$ Full range is –40°C to 125°C.

[§] All typical values are at $T_A = 25$ °C.

[¶] Due to proximity of external components, ensure that coupling is not originating via stray capacitance between these external parts. Typically, this can be detected, as this type of coupling increases at higher frequencies.

operating conditions, V_{CC} = ± 15 V, T_A = $25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
SR	Slew rate at unity gain	R_L = 1 M Ω , C_L = 30 pF, V_I = ±10 V (see Figure 1)	0.5	V/μs
B ₁	Unity-gain bandwidth	$R_L = 1 M\Omega$, $C_L = 20 pF$ (see Figure 1)	1.2	MHz
V _n	Equivalent input noise voltage	$R_S = 100 \Omega$, $V_I = 0 V$, $f = 1 kHz$ (see Figure 2)	35	nV/√ Hz

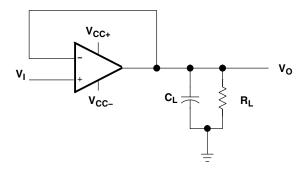


Figure 1. Unity-Gain Amplifier

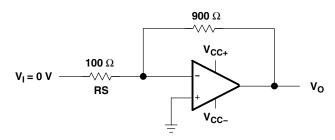


Figure 2. Noise-Test Circuit





11-Apr-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing		Qty	(2)		(3)		(4)	
LM2902KAVQDRG4Q1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2902KAQ	Samples
LM2902KAVQDRQ1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2902KAQ	Samples
LM2902KAVQPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2902KAQ	Samples
LM2902KAVQPWRQ1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2902KAQ	Samples
LM2902KVQDRG4Q1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2902KVQ	Samples
LM2902KVQDRQ1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2902KVQ	Samples
LM2902KVQPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2902KVQ	Samples
LM2902KVQPWRQ1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2902KVQ	Samples
LM2902QDRG4Q1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2902Q1	Samples
LM2902QDRQ1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2902Q1	Samples
LM2902QPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2902Q1	Samples
LM2902QPWRQ1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2902Q1	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

11-Apr-2013

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL. Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF LM2902-Q1:

Catalog: LM2902

■ Enhanced Product: LM2902-EP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 14-Mar-2013

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM2902KAVQPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902KAVQPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902KVQPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902KVQPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902QPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902QPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

All difficusions are nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM2902KAVQPWRG4Q1	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2902KAVQPWRQ1	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2902KVQPWRG4Q1	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2902KVQPWRQ1	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2902QPWRG4Q1	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2902QPWRQ1	TSSOP	PW	14	2000	367.0	367.0	35.0

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
 - Sody length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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